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**AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) A lamp assembly comprising:
  - a. a housing having an interior surface and an exterior surface;
  - b. a conductive lead frame insert molded into the housing the conductive lead frame being so that the conductive lead frame is encapsulated in between the interior surface and the exterior surface of the housing, the conductive lead frame having and comprising at least one positive connection pad, located at the interior surface of the housing, at least one negative connection pad located substantially adjacent to the at least one positive connection pad at the interior surface of the housing, and a means to electrically communicate the at least one positive connection pad and the at least one negative connection pad to the exterior surface of the housing so that electricity can pass through the lead frame and the at least one positive connection pad and at least one negative connection pad; and
  - c. at least one light emitting diode light source positioned inside the housing and electrically connected across the at least one negative connection pad and the at least one positive connection pad.
2. (Previously Presented) The lamp assembly of claim 1, further comprising LED drive components electrically connected across the at least one negative connection pad and the at least one positive connection pad.
3. (Previously Presented) The lamp assembly of claim 1, further comprising a lens attached to the housing.

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4. (Previously Presented) The lamp assembly of claim 1, wherein the interior surface is formed into a reflector arranged to reflect light emitted from the at least one light emitting diode light source out of the housing in a desired pattern.

5. (Previously Presented) The lamp assembly of claim 1, where the at least one light emitting diode light source may be operable to emit light of any wavelength.

6. (Previously Presented) The lamp assembly of claim 1, where the conductive lead frame comprises a positive lead line and a negative lead line electrically connected respectively to the at least one positive connection pad and the at least one negative connection pad.

7. (Previously Presented) The lamp assembly of claim 6, wherein the means for electrically communicate the at least one positive connection pad and at least one negative connection pad comprises a positive terminal extending from the exterior of the housing and electrically connected to the positive lead line, and a negative terminal extending from the exterior surface of the housing and electrically connected to the negative lead line, where the positive terminal and the negative terminal can be connected to an external source of electricity.

8. - 18. (Canceled)

19. (Previously Presented) A method for manufacturing a lamp assembly, the method comprising the steps of:

- a. providing a conductive lead frame, the conductive lead frame comprising at least one positive connection pad and at least one negative connection pad;
- b. inserting the conductive lead frame into a molding cavity;
- c. molding a housing with an interior surface and an exterior surface around the lead frame in the molding cavity by injecting a plastic resin into the molding cavity, so that

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the conductive lead frame is encapsulated by the housing and the at least one positive connection pad and at least one negative connection pad extend to the interior surface of the housing;

d. removing the housing with the lead frame molded therein from the molding cavity; and

e. electrically connecting at least one light emitting diode to the lead frame across said at least one positive connection pad and said at least one negative connection pad inside the housing.

20. (Previously Presented) The method of claim 19 wherein the provided lead frame further comprises a plurality of terminal holes, at least one positive lead line, and at least one negative lead line electrically connected to one another and the at least one positive connection pad and at least one negative connection pad.

21. (Previously Presented) The method of claim 20 wherein the provided lead frame further comprises a plurality of tie bars that hold the lead frame together.

22. (Previously Presented) The method of claim 21 further comprising the step of removing the tie bars from the lead frame.

23. (Previously Presented) The lamp assembly of claim 1 wherein the light emitting diode light source may be operable to emit light of any combination of wavelengths.